



SOT813-5

plastic thermal enhanced very thin quad flat package; no leads; 72 terminals

8 February 2016

Package information

1. Package summary

| | |
|---------------------------------------|------------------------------------------------------------|
| Terminal position code | Q (quad) |
| Package type descriptive code | HVQFN72 |
| Package type industry code | HVQFN72 |
| Package style descriptive code | HVQFN (thermal enhanced very thin quad flatpack; no leads) |
| Package style suffix code | NA (not applicable) |
| Package body material type | P (plastic) |
| JEDEC package outline code | MO-220 |
| Mounting method type | S (surface mount) |
| Issue date | 13-6-2013 |

Table 1. Package summary

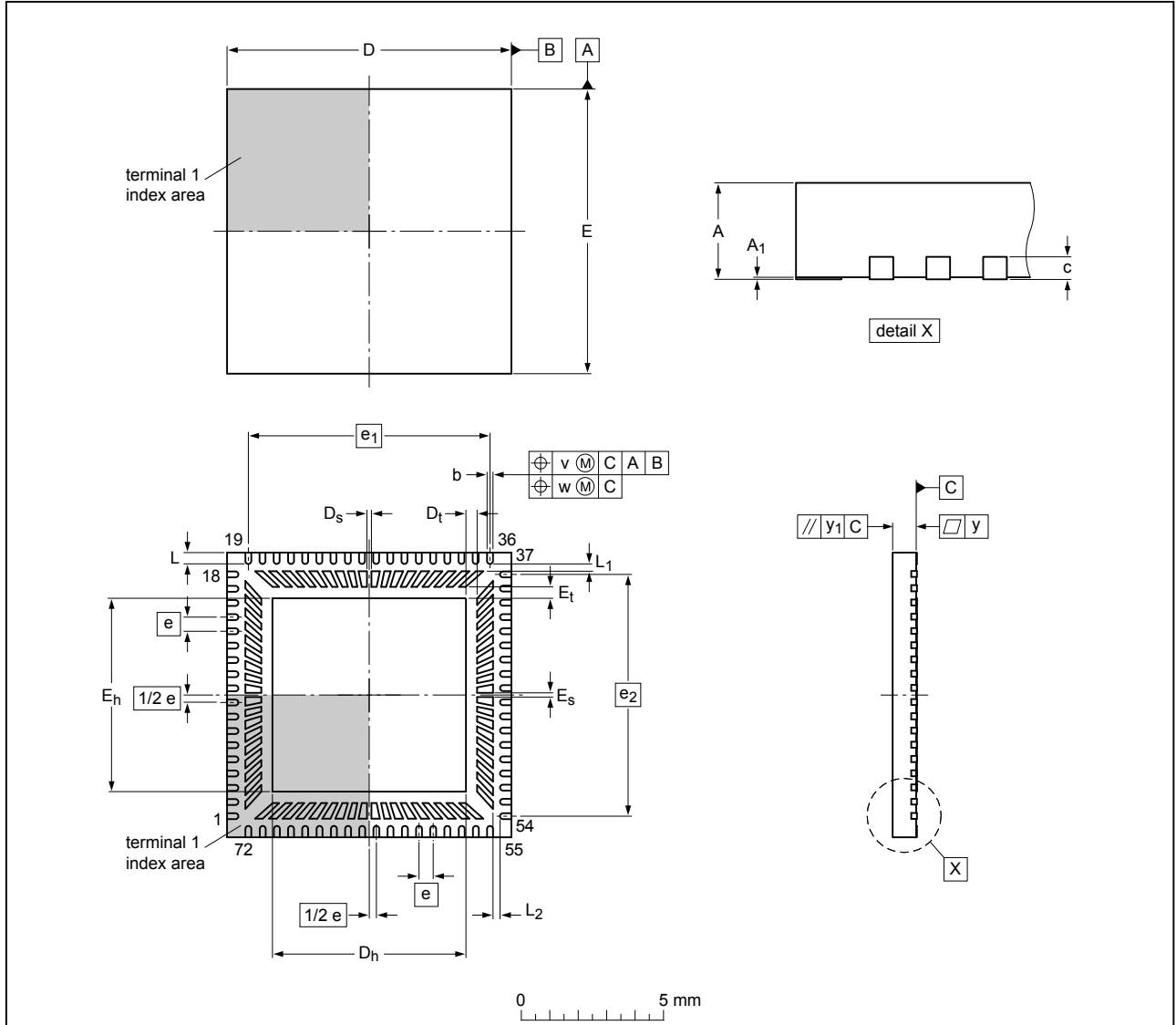
| Symbol | Parameter | Min | Typ | Nom | Max | Unit |
|----------------|--------------------------------|-----|-----|------|------|------|
| D | package length | 9.9 | - | 10 | 10.1 | mm |
| E | package width | 9.9 | - | 10 | 10.1 | mm |
| A | seated height | 0.8 | - | 0.85 | 1 | mm |
| e | nominal pitch | - | - | 0.5 | - | mm |
| n ₂ | actual quantity of termination | - | - | 72 | - | |



2. Package outline

HVQFN72: plastic thermal enhanced very thin quad flat package; no leads; 72 terminals; body 10 x 10 x 0.85 mm

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Dimensions (mm are the original dimensions)

| Unit | A | A ₁ | b | c | D ⁽¹⁾ | D _h | D _s | D _t | E ⁽¹⁾ | E _h | E _s | E _t | e | e ₁ | e ₂ | L | L ₁ | L ₂ | v | w | y | y ₁ |
|--------|------|----------------|------|-----|------------------|----------------|----------------|----------------|------------------|----------------|----------------|----------------|-----|----------------|----------------|------|----------------|----------------|-----|------|------|----------------|
| max | 1.00 | 0.05 | 0.30 | | 10.1 | 6.95 | 0.20 | 0.45 | 10.1 | 6.95 | 0.20 | 0.45 | | | | 0.50 | | | | | | |
| mm nom | 0.85 | 0.02 | 0.21 | 0.2 | 10.0 | 6.80 | 0.15 | 0.40 | 10.0 | 6.80 | 0.15 | 0.40 | 0.5 | 8.5 | 8.5 | 0.40 | 0.25 | 0.25 | 0.1 | 0.05 | 0.05 | 0.1 |
| min | 0.80 | 0.00 | 0.18 | | 9.9 | 6.65 | 0.10 | 0.35 | 9.9 | 6.65 | 0.10 | 0.35 | | | | 0.30 | | | | | | |

Notes

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included
2. Mold flash on exposed inner terminals is allowed

sot813-5_po

| Outline version | References | | | European projection | Issue date |
|-----------------|------------|--------|-------|---------------------|------------------------|
| | IEC | JEDEC | JEITA | | |
| SOT813-5 | | MO-220 | | | -13-06-06- 13-06-13 |

Fig. 1. Package outline HVQFN72 (SOT813-5)

3. Legal information

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